



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of: Agarwal et al.

Patent No. 6,833,576

Issued: December 21, 2004

Confirmation No. 6254

For: METHODS FOR FORMING AND
INTEGRATED CIRCUIT STRUCTURES
CONTAINING RUTHENIUM AND
TUNGSTEN CONTAINING LAYERS

Examiner: David Vu

Art Unit: 2818

Attorney Reference No. 6047-61466-01

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Attorney
for Applicant(s)

Date Mailed January 24, 2005

TRANSMITTAL LETTER

The undersigned requests the following enclosed references be placed in the file for the patent referenced above:

- ☒ Ha et al., U.S. Patent 5,970,309
- ☒ Sun et al., U.S. Patent 6,010,931
- ☒ Please return the enclosed postcard to confirm that the items listed above have been received.

Respectfully submitted,

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cc: Docketing